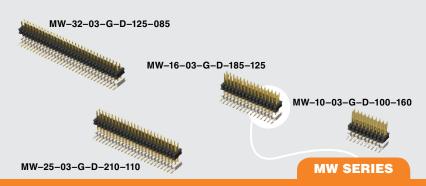




(1.00 mm) .0394"



MICRO BOARD HEA

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MW

Insulator Material:

Top: Black LCP Bottom: Natural LCP Terminal Material: Phosphor Bronze Operating Temp Range: -55 °C to +125 °C

Plating: Au over 50 μ" (1.27 μm) Ni RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-30) (0.15 mm) .006" max (31-50)* *(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Mates with:

.M, MLE

ALSO AVAILABLE (MOQ Required)

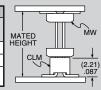
- End shrouds
- · End shrouds with guide posts

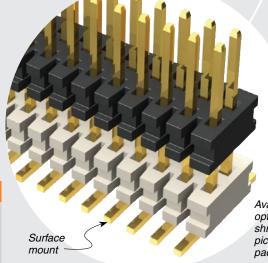
Contact Samtec.



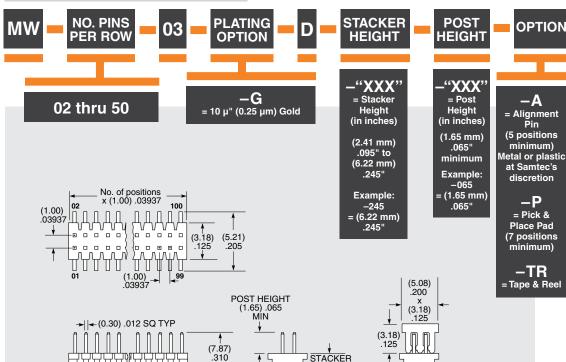
APPLICATIONS

EXAMPLES		
LEAD STYLE		MATED
MW	CLM HEIGHT*	
-163-065	-02	(6.35) .250
-233-065		(8.13) .320
*Processing conditions will affect mated height.		





Available with optional end shrouds and pick-and-place pads



HEIGHT (2.41)

to (6.22)

245

-P OPTION

Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice

`.310 MAX

LENGTH

(1.49)

(1.80) [.071 _[